

**MICROCOMPONENT INTERCONNECTION UTILIZING  
POST-ASSEMBLY ACTIVATION**

**ABSTRACT**

**[0044]** A new process and structure for microcomponent interconnection utilizing a post-assembly activated junction compound. In one embodiment, first and second microcomponents having respective first and second contact areas are provided. A junction compound is formed on one of the first and second contact areas, and the first and second contact areas are positioned adjacent each other on opposing sides of the junction compound. The junction compound is then activated to couple the first and second microcomponents.